

A1  
a bead of an adhesive mixed with a zeolite applied between the back plate glass and the substrate glass; and  
a mirror processed on the substrate glass.

10. The micro-electromechanical systems based device package of claim 9, including the bead being applied around the perimeter of the mirror.

11. The micro-electromechanical systems based device package of claim 9, wherein the bead acts as a hermetic seal.

12. The micro-electromechanical systems based device package of claim 9, wherein the bead traps moisture and other contaminant gases that can be harmful to the mirror.

13. The micro-electromechanical systems based device package of claim 8, wherein the micro-electromechanical systems device includes an electronic display screen.

A2  
15. (Amended) The device of claim 14, wherein the first and second surfaces are selected from the group consisting of a glass surface, a metal surface, a polymer surface, a plastic surface, an alloy surface, and a ceramic surface.

A3  
6 25. (New) A micro-electromechanical systems based device package comprising:  
a back plate glass;  
a substrate glass; and  
a bead of an adhesive mixed with zeolites of different pore sizes applied between the back plate glass and the substrate glass, wherein the zeolites of different pore sizes are selected to absorb molecules of different diameters.

7 26. (New) The micro-electromechanical systems based device package of claim 25<sup>b</sup>, wherein some of the zeolites have a pore size to allow absorption of molecules having a diameter of up to ten angstroms.

8 ~~27~~ (New) The micro-electromechanical systems based device package of claim ~~25~~<sup>6</sup>, wherein some of the zeolites have a pore size to allow absorption of molecules having a diameter of less than two angstroms.

9 ~~28~~ (New) The micro-electromechanical systems based device package of claim ~~25~~<sup>6</sup>, wherein the pore sizes of some of the zeolites allow absorption of nitrogen and carbon dioxide molecules.

13 cont  
10 ~~29~~ (New) A micro-electromechanical systems based device package comprising:  
a back plate glass;  
a substrate glass; and  
a bead of an adhesive mixed with a zeolite applied between the back plate glass and the substrate glass, wherein the zeolite is selected to have a pore size which allows the zeolite to absorb a contaminant gas that is outgassed by components of the package.

15 21  
b  
11 ~~30~~ (New) The micro-electromechanical systems based device package of claim ~~28~~<sup>10</sup>, wherein the zeolite has a pore size that allows it to absorb aromatic branched-chain hydrocarbons.

b  
12 ~~31~~ (New) The micro-electromechanical systems based device package of claim ~~28~~<sup>10</sup>, wherein the zeolite has a pore size that allows it to absorb hydrogen molecules.

b  
13 ~~32~~ (New) The micro-electromechanical systems based device package of claim ~~28~~<sup>10</sup>, wherein the zeolite has a pore size that allows it to absorb nitrogen and carbon dioxide molecules.